SOD323 SILICON HIGH CURRENT SCHOTTKY BARRIER DIODE "SuperBAT"

SOD323

FEATURES

- Low V_F
- High current capability
- Miniature surface mount package

APPLICATIONS

- DC DC converters
- Mobile telecomms
- PCMCIA
- **DEVICE MARKING**
- Partmark detail BD

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	VALUE	UNIT
Continuous Reverse Voltage	V _R	40	V
Forward Current (Continuous)	I _F	400	mA
Forward Voltage @ I _F =400mA	V _F	500	mV
Average Peak Forward Current; D.C. = 50%	I _{FAV}	1000	mA
$ \begin{array}{ l l l l l l l l l l l l l l l l l l l$	I _{FSM}	6.75 3	A A
Power Dissipation at T _{amb} =25°C	P _{tot}	250	mW
Storage Temperature Range	T _{stg}	-55 to +150	°C
Junction Temperature	Tj	125	°C

ELECTRICAL CHARACTERISTICS (at T_{amb} = 25°C unless otherwise stated)

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS
Reverse Breakdown Voltage	V _{(BR)R}	40	60		V	I _R =200μA
Forward Voltage	V _F		270 300 370 425 550 640 810 440	300 350 460 500 670 780 1050	mV mV mV mV mV mV mV	$I_{F}=50mA \\ I_{F}=100mA \\ I_{F}=250mA \\ I_{F}=400mA \\ I_{F}=750mA \\ I_{F}=1500mA \\ I_{F}=1500mA \\ I_{F}=500mA, T_{amb}=100^{\circ}C$
Reverse Current	I _R		15	40	μA	V _R =30V
Diode Capacitance	CD		20		pF	f=1MHz,V _R =25V
Reverse Recovery Time	t _{rr}		10		ns	switched from I _F = 500mA to I _R = 500mA Measured at I _R = 50mA

ISSUE 4 - MARCH 2007

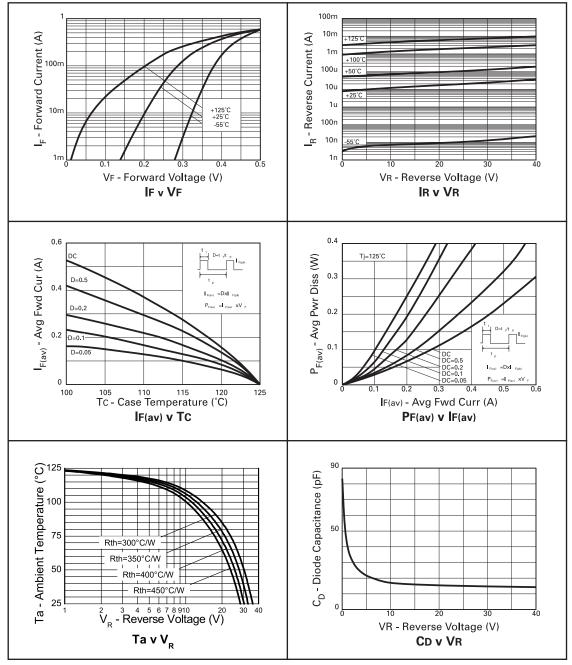






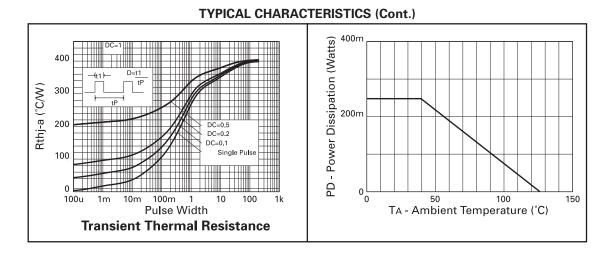
Partmark is for example only

Cathode



TYPICAL CHARACTERISTICS







NOTES:



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"Preview"Future device intended for production at some point. Samples may be available

"Active"Product status recommended for new designs

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"Not recommended for new designs"Device is still in production to support existing designs and production

"Obsolete"Production has been discontinued

Datasheet status key:

"Draft version"This term denotes a very early datasheet version and contains highly provisional

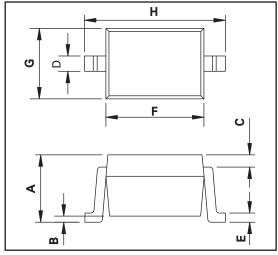
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PACKAGE OUTLINE



PACKAGE DIMENSIONS

DIM	Millimeters		DIM	Millimeters		
	Min	Мах	DIN	Min	Max	
A	0.91	1.16	E	0.127	0.2	
В	-	0.1	F	1.52	1.77	
С	-	-	G	1.11	1.37	
D	0.33	0.4	Н	2.46	2.71	

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